Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic		Symbol	Value	Units
Drain-Source Voltage		V_{DSS}	30	V
Gate-Source Voltage	Continuous	V_{GSS}	±20	V
Drain Current	Continuous Pulsed	I_D	1.1 4.0	A

Thermal Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Units
Total Power Dissipation	P_D	500	mW
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	250	K/W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic		Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 4)							
Drain-Source Breakdown Voltage		BV_{DSS}	30	—	—	V	V_{GS} = 0V, I_D = 250μA
Zero Gate Voltage Drain Current	@ T_J = 25°C @ T_J = 125°C	I_{DSS}	—	—	1.0 10	μA	V_{DS} = 24V, V_{GS} = 0V
Gate-Body Leakage		I_{GSS}	—	—	± 100	nA	V_{GS} = ± 12V, V_{DS} = 0V
ON CHARACTERISTICS (Note 4)							
Gate Threshold Voltage		$V_{GS(th)}$	1.0	—	3.0	V	V_{DS} = 10V, I_D = 1.0mA
Static Drain-Source On-Resistance		$R_{DS\ (ON)}$	—	—	0.170 0.150	Ω	V_{GS} = 4.5V, I_D = 0.5A V_{GS} = 10V, I_D = 1.0A
Forward Transconductance		g_{FS}	1.3	2.4	—	S	V_{DS} = 10V, I_D = 0.5A
DYNAMIC CHARACTERISTICS							
Input Capacitance		C_{iss}	—	150	—	pF	V_{DS} = 10V, V_{GS} = 0V f = 1.0MHz
Output Capacitance		C_{oss}	—	90	—	pF	
Reverse Transfer Capacitance		C_{rss}	—	30	—	pF	
Total Gate Charge		Q_g	—	5.5	—	nC	V_{DS} = 24V, I_D = 1.0A, V_{GS} = 10V
Gate-to-Source Charge		Q_{gs}	—	0.8	—	nC	
Gate-to-Drain Charge		Q_{gd}	—	1.3	—	nC	
SWITCHING CHARACTERISTICS							
Turn-On Delay Time		$t_{D(ON)}$	—	10	—	ns	V_{DD} = 10V, I_D = 0.5A, V_{GS} = 5.0V, R_{GEN} = 50Ω
Turn-Off Delay Time		$t_{D(OFF)}$	—	25	—	ns	
Turn-On Rise Time		t_r	—	15	—	ns	
Turn-Off Fall Time		t_f	—	45	—	ns	
SOURCE-DRAIN RATINGS (BODY DIODE)							
Continuous Source Current		I_S	—	—	0.54	A	—
Pulse Source Current		I_{SM}	—	—	4.0	A	—
Forward Voltage		V_{SD}	—	—	1.2	V	I_F = 1.0A, V_{GS} = 0V
Reverse Recovery Time		t_{rr}	—	35	—	ns	I_F = 1.0A, di/dt = 50A/μs

Notes: 4. Pulse width ≤ 300μs, duty cycle ≤ 2%.

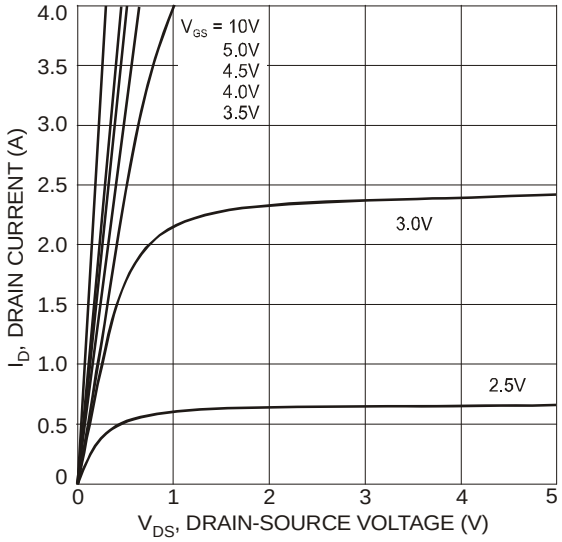


Fig. 1 On-Region Characteristics

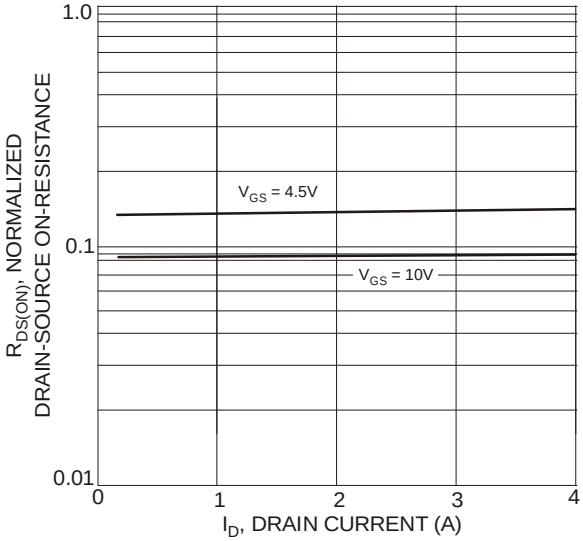


Fig. 2 On-Resistance vs. Drain Current

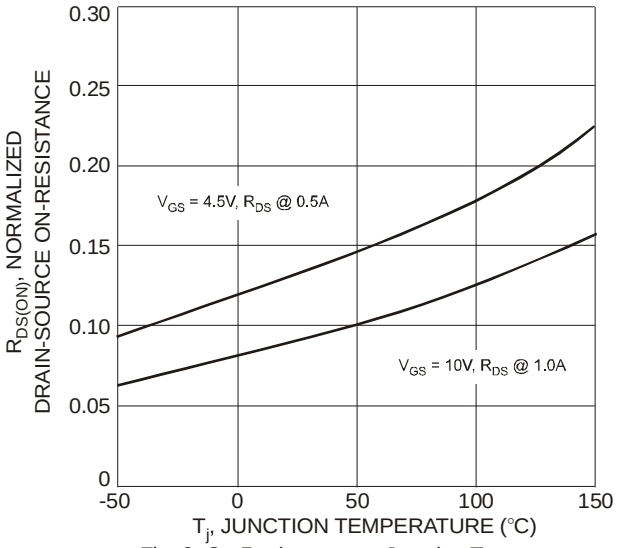


Fig. 3 On-Resistance vs. Junction Temperature

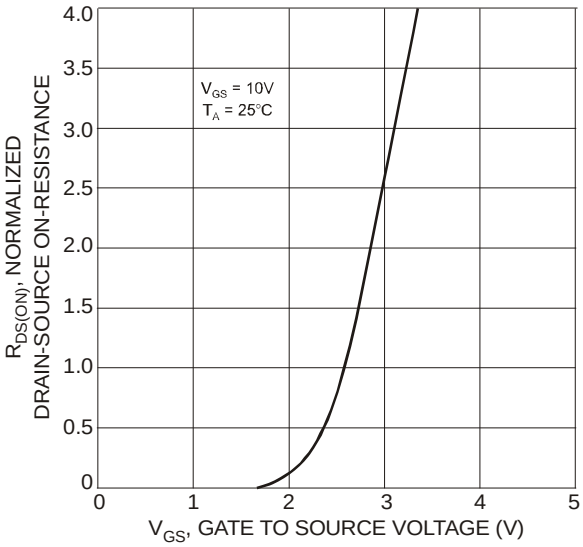
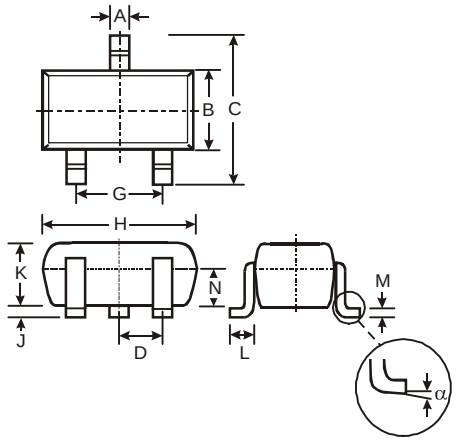


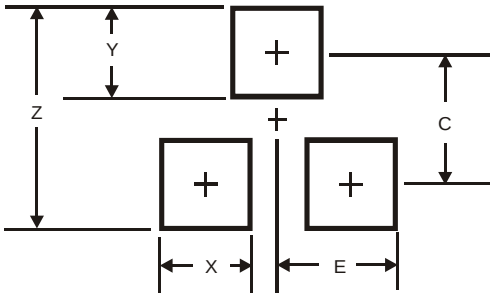
Fig. 4 On-Resistance vs. Gate-Source Voltage

Package Outline Dimensions



SC59			
Dim	**Min**	**Max**	**Typ**
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	-	-	0.95
G	-	-	1.90
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
N	0.70	0.80	0.75
α	0°	8°	-
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	3.4
X	0.8
Y	1.0
C	2.4
E	1.35